

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention

Elimination of RDL Using Tape Base Flip Chip on Flex for Die
Stacking

Application Number : 10/050507

Confirmation Number: 7687

First Named Applicant: Teck Lee

Attorney Docket Number: MTI-31607

Art Unit: 2813

Examiner: Jack SJ Chen

Search string: (6624060 or 20020027080 or 20030134450).pn



US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6624060	2003-09-23	Chen et al.		438	613

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20020027080	2002-03-07	Yoshioka et al.	A1	205	123
	2	20030134450	2003-07-17	Lee	A1	438	106

Signature

Examiner Name	Date